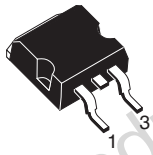
STB70NFS03L

N-channel - 30V - 0.0075Ω - 70A D²PAK
STripFET™ Power MOSFET plus schottky rectifier

General features

Type	V_{DSS}	$R_{DS(on)}$	I_D
STB70NFS03L	30V	<0.0095Ω	70A
Schottky	$I_{F(AV)}$	V_{RRM}	$V_{F(MAX)}$
	3A	30V	0.51V

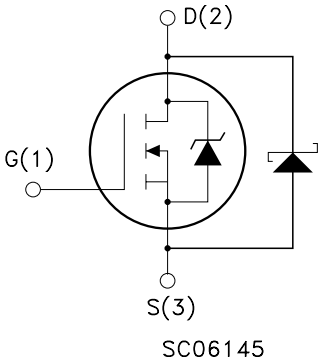


D²PAK

Description

This product associates a Power MOSFET of the third genaration of STMicroelectronics unique "Single Feature Size" strip-based process and a low drop schottky diode. The transistor shows the best trade-off between on-resistance and gate charge. Used as low side in buck regulators, the product is the solution in terms of conduction losses and space saving.

Internal schematic diagram



Applications

- Switching application

Obsolete Product(s) - Obsolete Product(s)

Order codes

Part number	Marking	Package	Packaging
STB70NFS03L	B70NFS03L	D²PAK	Tape & reel

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2 Electrical characteristics 4

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3 Test circuits 8

4 Package mechanical data 9

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Obsolete Product(s) - Obsolete Product(s)

1 Electrical ratings

Table 1. Mosfet absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V_{GS} = 0)	30	V
V_{GS}	Gate- source voltage	± 18	V
I_D	Drain current (continuous) at T_C = 25°C	70	A
I_D	Drain current (continuous) at T_C = 100°C	50	A
I_{DM} (1)	Drain current (pulsed)	280	A
P_{TOT}	Total dissipation at T_C = 25°C	100	W
	Derating factor	0.67	W/°C
dv/dt (2)	Peak diode recovery voltage slope	5.5	V/ns
E_{AS} (3)	Single pulse avalanche energy	500	mJ
T_{stg}	Storage temperature	-55 to 175	°C
T_J	Operating junction temperature		

1. Pulse width limited by safe operating area
2. $I_{SD} \leq 70A$, di/dt ≤ 350A/µs, V_{DD} = 80% $V_{(BR)DSS}$
3. Starting Tj = 25°C, V_{DD} = 25V

Table 2. Schottky absolute maximum ratings

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		30	V
$I_{F(RMS)}$	RMS forward current		20	A
$I_{F(AV)}$	Average forward current	T_L=125°C δ=0.5	3	A
I_{FSM}	Surge non repetitive forward current	tp=10ms Sinusoidal	75	A
dv/dt	Critical rate of rise of reverse voltage		10000	v/µs

Table 3. Thermal data

Symbol	Parameter	Value	Unit
Rthj-amb	Thermal resistance junction-amb max	1.5	°C/W
Rthj-case	Thermal resistance junction-case max	62.5	°C/W
T_l	Maximum lead temperature for soldering purpose	300	°C

Obsolete Product(s) - Obsolete Product(s)

2 Electrical characteristics

(Tcase =25°C unless otherwise specified)

Table 4. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 250µA, V_{GS} = 0	30			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = Max rating V_{DS} = Max rating, T_C=125°C			200 20	µA mA
I_{GSS}	Gate-body leakage current (V_{DS} = 0)	V_{GS} = ± 18V			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250µA	1			V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS} = 10V, I_D = 35A V_{GS} = 5V, I_D = 18A		0.0075 0.0135	0.0095 0.018	Ω Ω

Table 5. Shottcky static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_R	Reverse leakage current	T_j = 25°C V_R = 30V T_j = 100°C V_R = 30V		 0.03	0.2 100	mA mA
V_F	Zero gate voltage drain current (V_{GS} = 0)	T_j = 25°C I_F = 3A T_j = 125°C I_F = 3A		 0.425	0.51 0.46	V V

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs}	Forward transconductance	V_{DS} = 25V, I_D = 35A		25		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0		1440 560 135		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 15V, I_D = 70A, V_{GS} = 5V (see *Figure 11*)		22.5 9 12	30	nC nC nC

Obsolete Product(s) - Obsolete Product(s)

Table 7. Switching times

Symbol	Parameter	Test Conditions	Min.	Typ.	Max	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	V_{DD} = 15V, I_D = 35A, R_G = 4.7Ω, V_{GS} = 5V (see *Figure 10*)		22 165		ns ns
$t_{d(off)}$ t_f	Turn-off delay time Fall time	V_{DD} = 15V, I_D = 35A, R_G = 4.7Ω, V_{GS} = 5V (see *Figure 10*)		21 25		ns ns

Table 8. Source drain diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} I_{SDM} (1)	Source-drain current Source-drain current (pulsed)				70 280	A A
V_{SD} (2)	Forward on voltage	I_{SD} = 70A, V_{GS} = 0			1.3	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 70A, di/dt = 100A/µs V_{DD} = 20V, T_j = 150°C (see *Figure 15*)		42 52 2.5		ns nC A

1. Pulse width limited by safe operating area
2. Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %

Obsolete Product(s) - Obsolete Product(s)

2.1 Electrical characteristics (curves)

Figure 1. Output characterisics

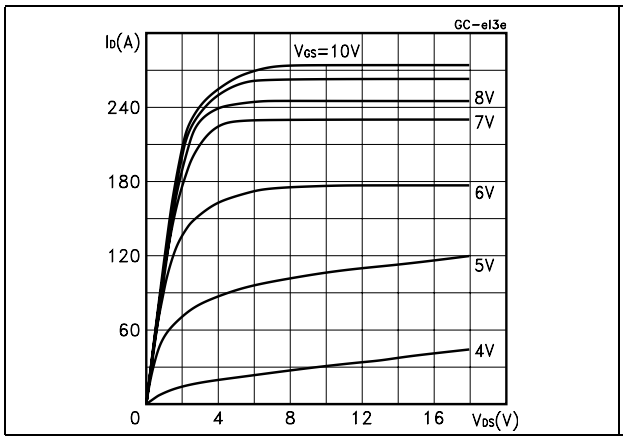


Figure 2. Transfer characteristics

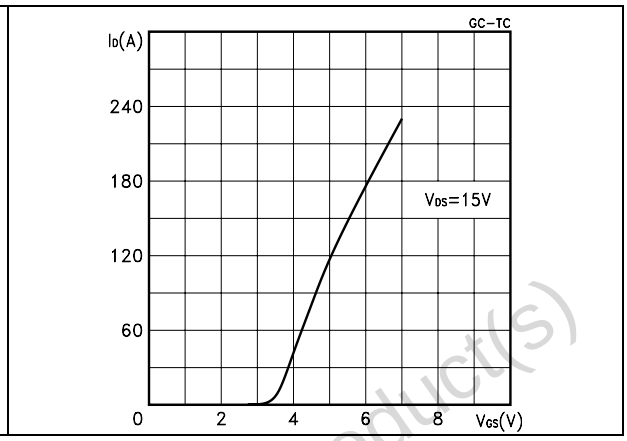


Figure 3. Source-drain diode forward characteristics

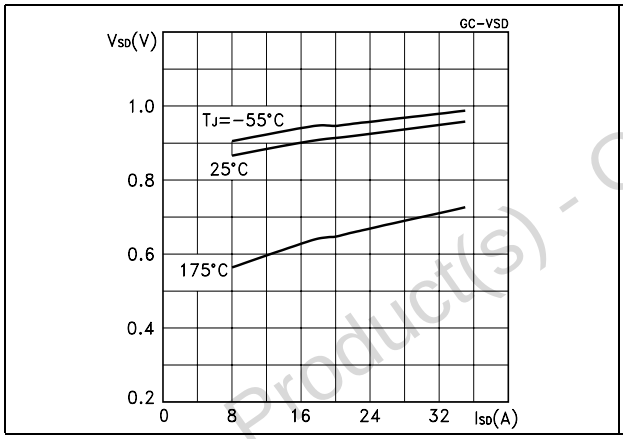


Figure 4. Static drain-source on resistance

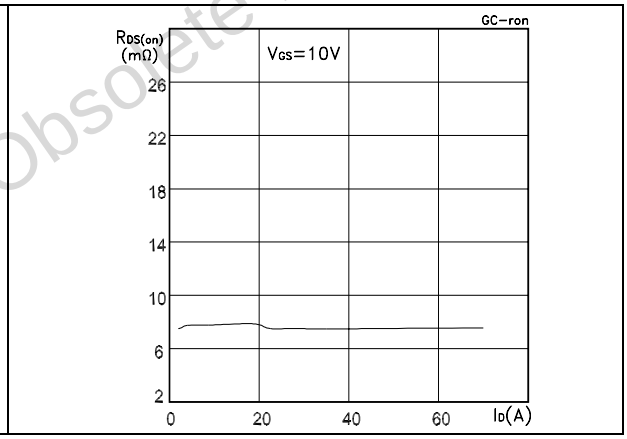


Figure 5. Gate charge vs gate-source voltage

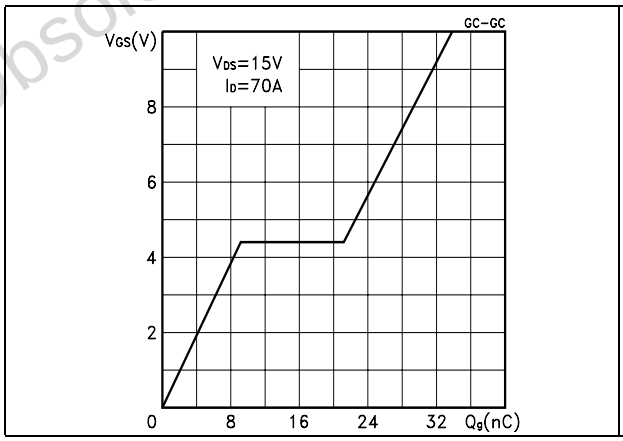
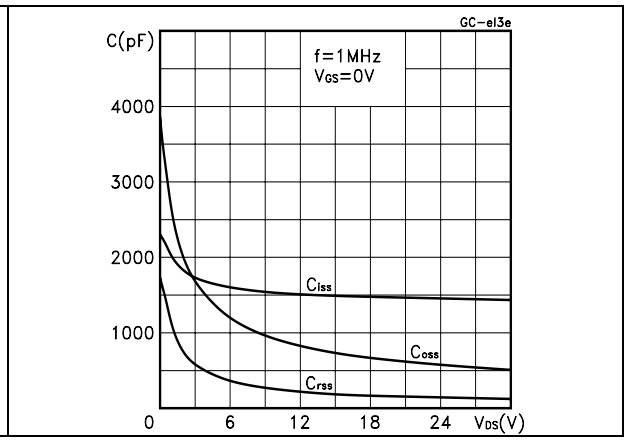


Figure 6. Capacitance variations



Obsolete Product(s) - Obsolete Product(s)

Figure 7. Normalized gate threshold voltage vs temperature

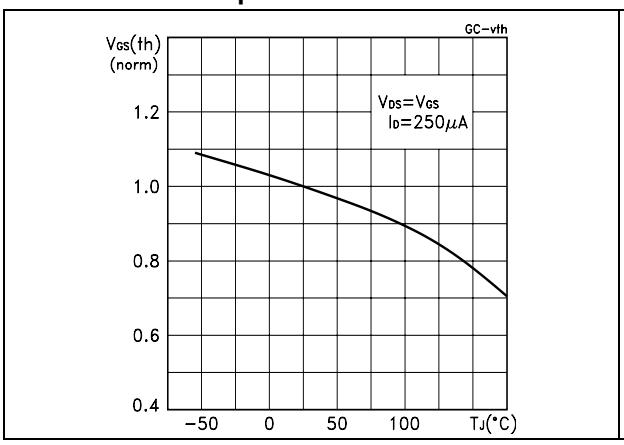


Figure 8. Normalized on resistance vs temperature

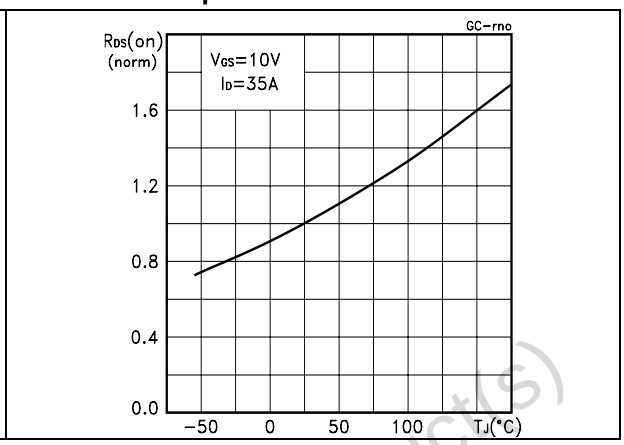
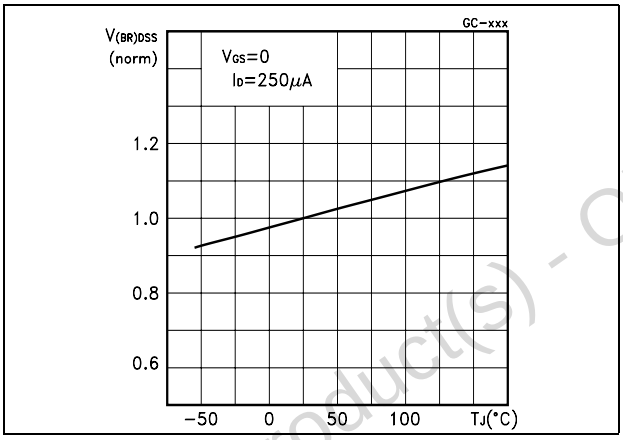


Figure 9. Normalized BV_{DSS} voltage vs temperature



Obsolete Product(s) - Obsolete Product(s)

3 Test circuits

Figure 10. Switching times test circuit for resistive load

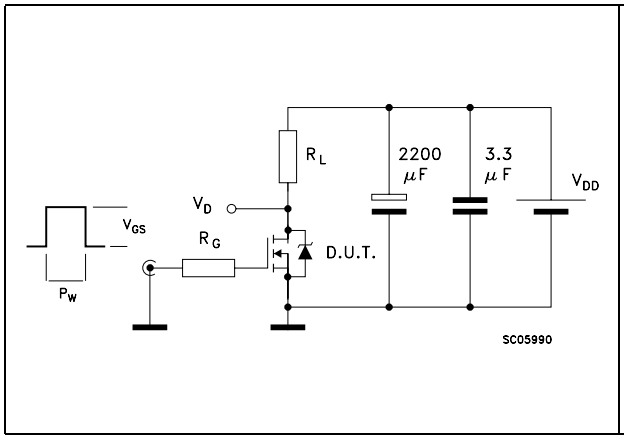


Figure 11. Gate charge test circuit

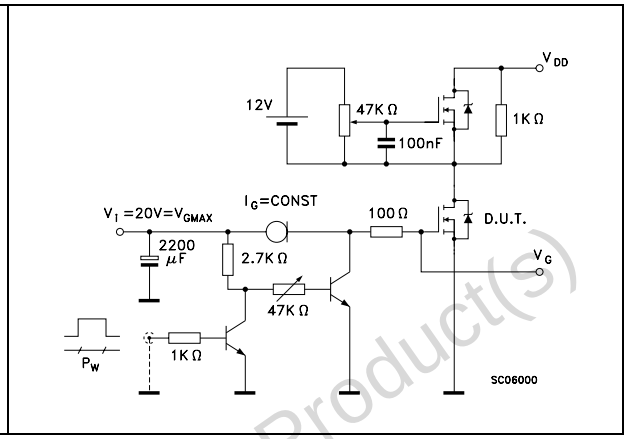


Figure 12. Test circuit for inductive load switching and diode recovery times

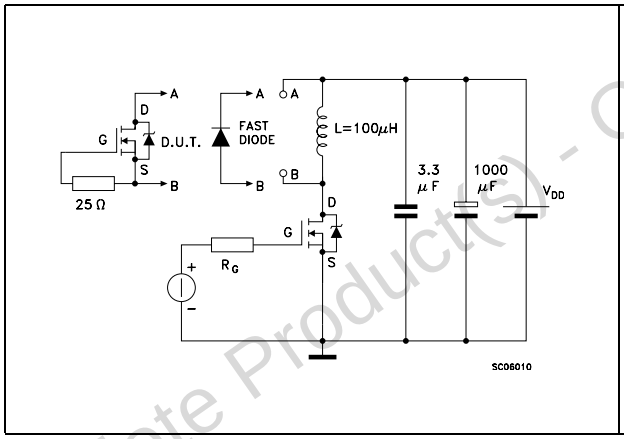


Figure 13. Unclamped inductive load test circuit

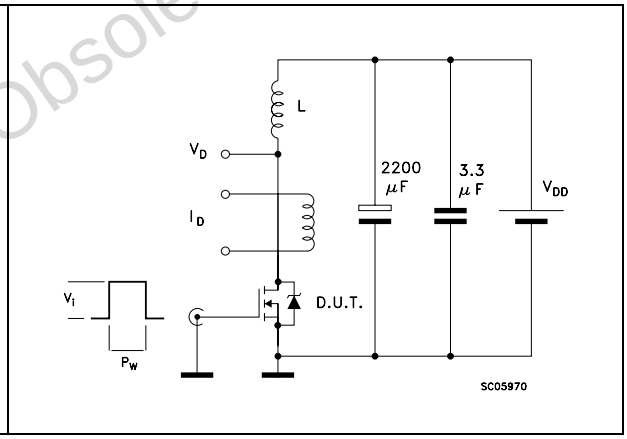


Figure 14. Unclamped inductive waveform

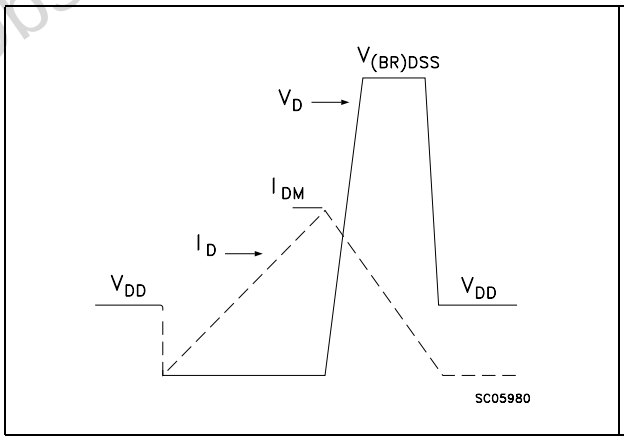
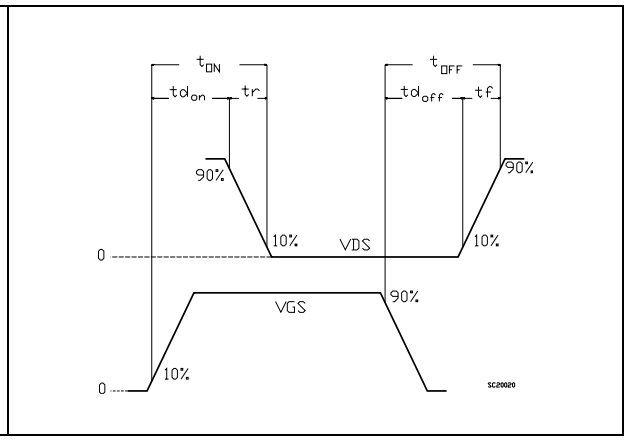


Figure 15. Switching time waveform



Obsolete Product(s) - Obsolete Product(s)

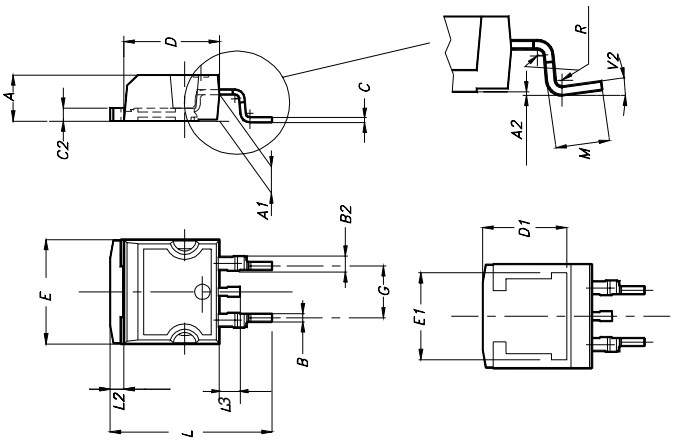
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: *www.st.com*

Obsolete Product(s) - Obsolete Product(s)

D^2PAK MECHANICAL DATA

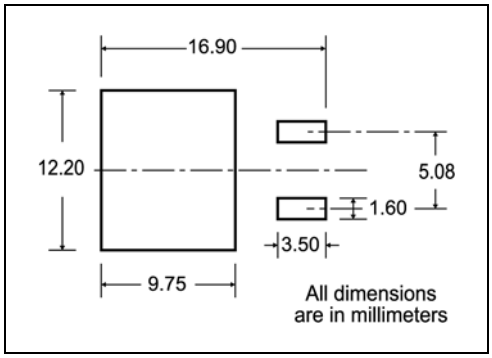
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0º		4º			



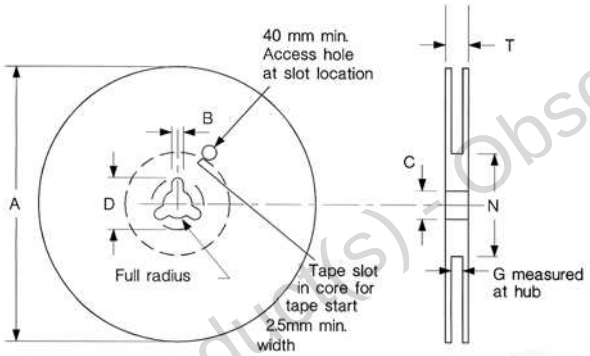
Obsolete Product(s) - Obsolete Product(s)

5 Packaging mechanical data

D²PAK FOOTPRINT



TAPE AND REEL SHIPMENT



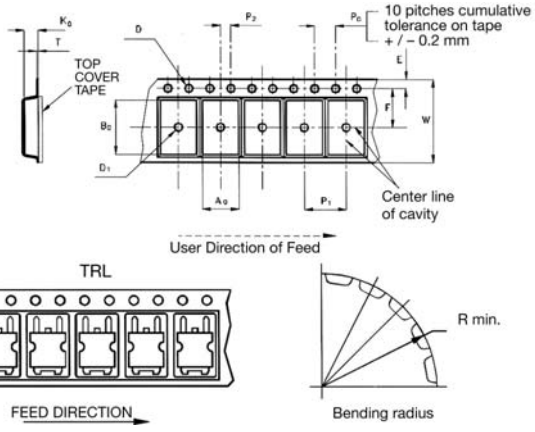
REEL MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A		330		12.992
B	1.5		0.059	
C	12.8	13.2	0.504	0.520
D	20.2		0795	
G	24.4	26.4	0.960	1.039
N	100		3.937	
T		30.4		1.197

BASE QTY	BULK QTY
1000	1000

TAPE MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A0	10.5	10.7	0.413	0.421
B0	15.7	15.9	0.618	0.626
D	1.5	1.6	0.059	0.063
D1	1.59	1.61	0.062	0.063
E	1.65	1.85	0.065	0.073
F	11.4	11.6	0.449	0.456
K0	4.8	5.0	0.189	0.197
P0	3.9	4.1	0.153	0.161
P1	11.9	12.1	0.468	0.476
P2	1.9	2.1	0.075	0.082
R	50		1.574	
T	0.25	0.35	0.0098	0.0137
W	23.7	24.3	0.933	0.956



* on sales type

Obsolete Product(s) - Obsolete Product(s)

6 Revision history

Table 9. Revision history

Date	Revision	Changes
09-Sep-2004	8	New datasheet according to PCN DSG/CT/2C13 marking: STB70NFS03I@
05-Jul-2006	9	New template, new value on *Table 4.: On /off states*

Obsolete Product(s) - Obsolete Product(s)

Obsolete Product(s) - Obsolete Product(s)

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